GBU6005 THRU GBU610



GLASS PASSIVATED SINGLE-PHASE BRIDGE RECTIFIER

REVERSE VOLTAGE: 50 to 1000 VOLTS FORWARD CURRENT: 6.0 AMPERE

FEATURES

· Glass passivated chip junction

· Ideal for printed circuit board

Plastic material has Underwriters Laboratory
 Flammability Classification 94V-0

· Reliable low cost construction utilizing molded plastic technique

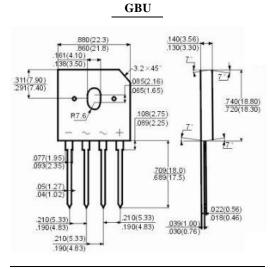
MECHANICAL DATA

Case: Molded plastic, GBU

Epoxy: UL 94V-O rate flame retardant

Terminals: Leads solderable per MIL-STD-202,

method 208 guaranteed Mounting position: Any Weight: 0.15ounce, 4.0gram



Dimensions in inches and (millimeters)

Maximum Ratings and Electrical Characteristics

Ratings at $25\,^\circ\!\!\mathrm{C}$ ambient temperature unless otherwise specified.

Single phase, half wave, 60Hz, resistive or inductive load.

For capacitive load, derate current by 20%.

	Symbols	GBU6005	GBU601	GBU602	GBU604	GBU606	GBU608	GBU610	Units
Maximum Recurrent Peak Reverse Voltage	V _{RRM}	50	100	200	400	600	800	1000	Volts
Maximum RMS Voltage	V_{RMS}	35	70	140	280	420	560	700	Volts
Maximum DC Blocking Voltage	V _{DC}	50	100	200	400	600	800	1000	Volts
Maximum Average Forward T _C =100℃	т	6.0							Amp
Rectified Current at (Note 1),(Note 2)	$I_{(AV)}$								
Peak Forward Surge Current,									
8.3ms single half-sine-wave	I _{FSM} 175							Amp	
superimposed on rated load (JEDEC method)									
Maximum Forward Voltage	$\mathbf{V}_{\mathbf{F}}$	1.0							Volts
at 6.0A DC and 25℃	V _F								
Maximum Reverse Current at T _A =25℃	т	5.0 500							uAmp
at Rated DC Blocking Voltage T _A =125℃	I_R								
Typical Junction Capacitance (Note 3)	C_{J}		2	10			94		pF
Typical Thermal Resistance (Note 1),(Note 2)	$R_{\theta JA}$	7.4						°C/W	
Typical Thermal Resistance (Note 1),(Note 2)	$R_{\theta JC}$	2.2							°C/W
Operating and Storage Temperature Range	T _J , Tstg	-55 to +150							°C

NOTES:

- 1- Units case mounted on 2.6 x 1.4 x 0.06" thick (6.5 x 3.5 x 0.15 cm) Al. Plate heatsink
- 2- Recommended mounting position is to bolt down on heatsink with silicone thermal compound for maximum heat transfer with #6 screws
- 3- Measured at 1 MHz and applied reverse voltage of 4.0 VDC.

RATINGS AND CHARACTERISTIC CURVES

Fig. 1 – Derating Curve
Output Rectified Current

6.0

Heatsink Mounting,
2.6 x 1.4 x 0.06" Thk
(6.5 x 3.5 x .15cm) AL. Plate

4.0

4.0

60 Hz Resistive or Inductive Load
0 50 100 150

Case Temperature (°C)

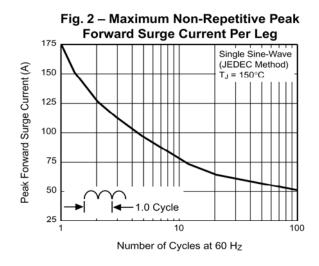


Fig. 3 – Typical Forward Characteristics Per Leg

100

100

T_J = 25°C
Pulse Width = 300µs
1% Duty Cycle

0.01
0.04
0.6
0.8
1.0
1.2
1.4
1.6
Instantaneous Forward Voltage (V)

